

This Page Is Inserted by IFW Operations
and is not a part of the Official Record

BEST AVAILABLE IMAGES

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images may include (but are not limited to):

- BLACK BORDERS
- TEXT CUT OFF AT TOP, BOTTOM OR SIDES
- FADED TEXT
- ILLEGIBLE TEXT
- SKEWED/SLANTED IMAGES
- COLORED PHOTOS
- BLACK OR VERY BLACK AND WHITE DARK PHOTOS
- GRAY SCALE DOCUMENTS

IMAGES ARE BEST AVAILABLE COPY.

**As rescanning documents *will not* correct images,
please do not report the images to the
Image Problem Mailbox.**

IN THE SPECIFICATION

Please rewrite the specification as set forth below.

Pages 18 and 19, the paragraph bridging these pages from page 18, line 21 to page 19, line 2, replace the bridging paragraph with:

According to features of the QFP 6 that is Embodiment 1, not only each inner lead 1b is fixed by the thin sheet-shaped tape substrate 5 but also, as shown in Fig. 2, a length (a) of a shorter side on the quadrilateral main surface 2c of the semiconductor chip 2 is twice or less than twice a distance (b). The distance (b) is between the semiconductor chip 2 and a tip of each of inner leads 1b which are placed at the farthest location on each center line 6a (X-axis or Y-axis) extending along a plane direction of the QFP 6.

Page 19, the first full paragraph, lines 3-6, the marked up paragraph is as follows:

That is, a relationship between the shorter side length (a) of the semiconductor chip 2 and a clearance (b) from the semiconductor chip 2 to such the tip of inner leads 1b that the tip is farthest from the semiconductor chip 2, is ~~a—2b a~~ $\leq 2b$.

Page 19, the second full paragraph, line 7, the marked up paragraph is as follows:

Further, the relationship is preferably $b - a - 2b \leq a$
 $\leq 2b$.

Page 19, the sixth full paragraph, lines 20-25, the marked up paragraph is as follows:

Fig. 3 shows a relationship between a pad pitch (P) of the semiconductor chip 2 which is mounted on the QFP 6 and has a narrow pad pitch, and a tip pitch (L) between such the inner leads 1b that a lead pitch between adjacent tips thereof is smallest (narrowest), in the QFP 6. The relationship is $P - L/2 - P \leq L/2$.

Pages 19 and 20, the paragraph bridging these pages from page 19, line 26 to page 20, line 3, replace the bridging paragraph with:

That is, because the pad pitch of the semiconductor chip 2 is less than or equal to $1/2$ of or $1/2$ less than the minimum value of the tip pitch between the adjacent inner leads 1b, effectiveness of the QFP 6 mounting the semiconductor chip 2 having a narrow pad pitch can be enhanced.

Page 20, the first full paragraph, lines 4-7, the marked up paragraph is as follows:

The pad pitch (P) of the semiconductor chip 2 is, for example, $60 \mu\text{m}$ and the minimum value (L) of the tip pitch between the inner leads 1b is, for example, $180 \mu\text{m}$. In this case, $(P=60 \mu\text{m}) - (L=180 \mu\text{m})/2 \leq (L=180 \mu\text{m})/2$ is obtained.

Page 23, the third full paragraph, lines 10-18, the marked up paragraph is as follows:

In the tape substrate 5 of each package area 1h, the semiconductor chip 2 is mounted on the surface of the inner lead arrangement side of the tape substrate 5, and is mounted such that a length of a shorter side of the main surface of the quadrilateral semiconductor chip 2 is less than or equal to twice of or twice less than a distance between the semiconductor chip 2 and a tip of an inner lead which is placed on the center line 6a of the QFP 6 in the plane direction and at such a location that the tip thereof is farthest from the center line 6a.

Page 23, the fourth full paragraph, lines 19-20, the marked up paragraph is as follows:

That is, a relationship described above is $a - 2b \leq a \leq 2b$ as shown in Fig. 2.